

## MICROFABRICATION

### RF/DC sputtering and e-beam evaporation

Manufacturer: Leybold

Model: UNIVEX900



### General Description:

The UNIVEX900 is an advanced coating system which can perform co-sputtering and e-beam evaporation in the same chamber in the same chamber. This tool is compatible with 8-inch wafers (200 mm) and can be used to deposit many materials such as metals, oxides or nitrides.

### Key Specifications:

- **Sputtering**
  - Max. thickness 3  $\mu\text{m}$
  - RF and DC sputtering
  - Co-sputtering possible
  - Reactive sputtering with  $\text{O}_2$  and/or  $\text{N}_2$
  - Conformal coatings
  - Target size 4"
  - Max. temperature substrate 400  $^{\circ}\text{C}$
  - Materials:  $\text{SiO}_2$ , Si doped, Al, Mo, AlN, Cu, Ag, Ti, Cr, Ni, PZT, Si (undoped),  $\text{Si}_x\text{N}_y$ ,  $\text{Ta}_2\text{O}_5$ ,  $\text{Al}_2\text{O}_3$ , SiC,...
- **E-beam evaporation**
  - Max. thickness 400 nm
  - High deposition rate
  - Lowest pressure achievable  $\sim 10^{-7}$  mbar
  - Materials: Ag, Al, Au, Cr, Pt, Ti, Ni

<b>Availability</b>	Use allowed for all researchers with permission
<b>Location</b>	Cleanroom C5 Europastraße 12 9524 Villach
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